Mechanical Data

- Surface Mount Package
- Weight: 0.0009 grams (Approximate)
- Max Soldering Temperature +260°C for 30 secs as per JEDEC J-STD-020
- Case Material – Molded Plastic, UL Flammability Rating 94V-0

Package Outline

Suggested Pad Layout

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These dimensions may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the ‘Z’ dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device Terminals and PCB tracking.
Minimum Packing Quantity

<table>
<thead>
<tr>
<th>Quantity</th>
<th>Tape Width</th>
<th>Part Number Suffix</th>
</tr>
</thead>
<tbody>
<tr>
<td>7&quot; Reel</td>
<td>3,000</td>
<td>8mm -7, -7R</td>
</tr>
<tr>
<td>7&quot; Reel</td>
<td>10,000</td>
<td>8mm -7B</td>
</tr>
</tbody>
</table>

Note: Package quantities given are for minimum packaging quantity only, not minimum order quantity. For minimum order quantity, please contact Sales Department.

Note: No mixed date codes or partial quantity (less than minimum packaging quantity) per packaging is allowed.

Note: In no case shall there be two or more consecutive components missing from any reel for any reason.

Device Tape Orientation

<table>
<thead>
<tr>
<th>Tape Width</th>
<th>Part Number Suffix</th>
<th>Tape Orientation</th>
</tr>
</thead>
<tbody>
<tr>
<td>8mm</td>
<td>-7B</td>
<td>Bar Denotes Base &amp; Emitter Side for BJT; Gate &amp; Source Side for MOS and Cathode Side for Diodes</td>
</tr>
<tr>
<td>8mm</td>
<td>-7</td>
<td>Bar Denotes Base &amp; Emitter Side for BJT; Gate &amp; Source Side for MOS and Cathode Side for Diodes</td>
</tr>
<tr>
<td>8mm</td>
<td>-7R</td>
<td>Bar Denotes Gate &amp; Source Side for MOS</td>
</tr>
</tbody>
</table>

Note: For part marking, refer to product datasheet.

Note: Tape and package drawings are not to scale and are shown for device tape orientation only.
Embossed Carrier Tape Specifications

a) \( P = 2.0\text{mm}, \) Part Number Suffix -7B

```
<table>
<thead>
<tr>
<th>Dimension</th>
<th>Value (mm)</th>
<th>Dimension</th>
<th>Value (mm)</th>
</tr>
</thead>
<tbody>
<tr>
<td>A0</td>
<td>0.69 ±0.05</td>
<td>E</td>
<td>1.75 ±0.10</td>
</tr>
<tr>
<td>B0</td>
<td>1.19 ±0.05</td>
<td>F</td>
<td>3.50 ±0.05</td>
</tr>
<tr>
<td>D</td>
<td>1.60 ±0.05</td>
<td>K0</td>
<td>0.53 ±0.05</td>
</tr>
<tr>
<td>D1</td>
<td>0.50 ±0.1</td>
<td>P</td>
<td>2.00 ±0.05</td>
</tr>
</tbody>
</table>
```

8mm

b) \( P = 4.0\text{mm}, \) Part Number Suffix -7, -7R

```
<table>
<thead>
<tr>
<th>Dimension</th>
<th>Value (mm)</th>
<th>Dimension</th>
<th>Value (mm)</th>
</tr>
</thead>
<tbody>
<tr>
<td>A0</td>
<td>0.69 ±0.05</td>
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<td>0.53 ±0.05</td>
</tr>
<tr>
<td>D1</td>
<td>0.50 ±0.1</td>
<td>P</td>
<td>2.00 ±0.05</td>
</tr>
</tbody>
</table>
```

The clearance between the component and the cavity must comply to the rotational and lateral movement requirement provided in the "Maximum Component Movement in Tape Pocket" section.
Embossed Carrier Tape Specifications (Continued)

Top cover tape thickness 0.10mm max.

Embosed Carrier

Cavity

Direction of Feed

R min. - 25mm

Bending radius of tape

100mm

1mm Max.

Tape

1mm Max.

250mm

Camber (Top View)

Allowable camber to be 1mm/100mm tape, non-cumulative
Maximum Component Movement in Tape Pocket

Component Lateral Movement
8mm Tape

0.5mm maximum

Maximum Component Rotation
Top View

Typical Pocket Centerline

Maximum Component Rotation
Side View

20°

Typical Component Centerline

Figure 1: Maximum Component Movement
Surface Mount Reel Specifications

<table>
<thead>
<tr>
<th>Tape Width</th>
<th>Reel Size</th>
<th>A (mm)</th>
<th>B Max (mm)</th>
<th>C (mm)</th>
<th>D Max (mm)</th>
<th>N Min (mm)</th>
<th>G (mm)</th>
<th>T Max (mm)</th>
</tr>
</thead>
<tbody>
<tr>
<td>8mm</td>
<td>7&quot;</td>
<td>178 ±2</td>
<td>20.0 +0.5 -0</td>
<td>13 ±0.5 -0.2</td>
<td>20.5 ±0.2</td>
<td>55 ±5</td>
<td>8.4 +1.5 -0.0</td>
<td>14.4</td>
</tr>
</tbody>
</table>

* Drive spokes optional. If used, dimensions with asterisks apply.

Tape Leader and Trailer Specifications

Note: There shall be a leader of at least 230mm which may consist of carrier tape and/or cover tape or a start tape followed by at least 160mm of empty carrier tape sealed with cover tape.

Note: There shall be a trailer of at least 160mm of empty carrier tape sealed with cover tape. The entire carrier tape must release from the reel hub as the last portion of the tape unwinds from the reel without damage to the carrier tape and the remaining components in the cavities.